

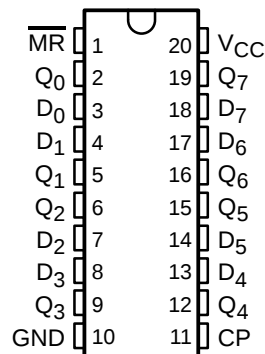
- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT273T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT273T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

description

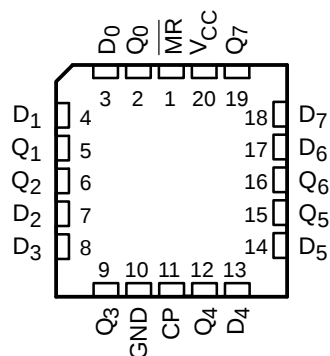
The 'FCT273T devices consist of eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered-clock (CP) and master-reset ($\overline{MR}$) inputs load and reset all flip-flops simultaneously. These devices are edge-triggered registers. The state of each D input (one setup time before the low-to-high clock transition) is transferred to the corresponding flip-flop's Q output. All outputs are forced low by a low logic level on the $\overline{MR}$ input.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

CY54FCT273T . . . D PACKAGE
CY74FCT273T . . . Q OR SO PACKAGE
(TOP VIEW)



CY54FCT273T . . . L PACKAGE
(TOP VIEW)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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CY54FCT273T, CY74FCT273T
8-BIT REGISTERS

SCCS020A – MARCH 1995 – REVISED OCTOBER 2001

ORDERING INFORMATION

T _A	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QSOP – Q	Tape and reel	5.8	CY74FCT273CTQCT	FCT273C
	SOIC – SO	Tube	5.8	CY74FCT273CTSOC	FCT273C
		Tape and reel	5.8	CY74FCT273CTSOCT	
	QSOP – Q	Tape and reel	7.2	CY74FCT273ATQCT	FCT273A
	SOIC – SO	Tube	7.2	CY74FCT273ATSOC	FCT273A
		Tape and reel	7.2	CY74FCT273ATSOCT	
	QSOP – Q	Tape and reel	13	CY74FCT273TQCT	FCT273
	SOIC – SO	Tube	13	CY74FCT273TSOC	FCT273
		Tape and reel	13	CY74FCT273TSOCT	
–55°C to 125°C	LCC – L	Tube	8.3	CY54FCT273ATLMB	

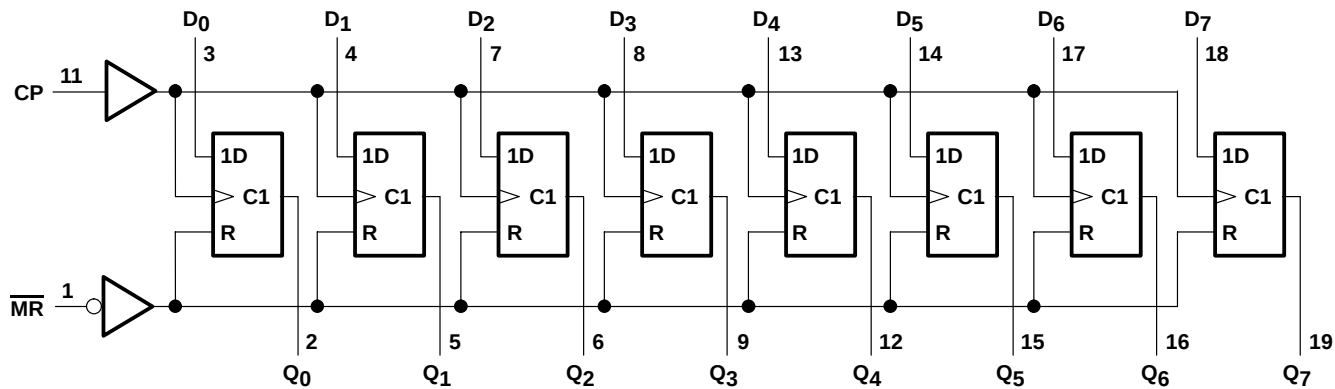
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS			OUTPUT Q	OPERATING MODE
MR	CP	D		
L	X	X	L	Reset (clear)
H	↑	h	H	Load '1'
H	↑	l	L	Load '0'

H = High logic level steady state, h = High logic level one setup time prior to low-to-high clock transition, L = Low logic level steady state, l = Low logic level one setup time prior to the low-to-high transition, X = Don't care, ↑ = Low-to-high clock transition

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package	68°C/W
SO package	58°C/W
Ambient temperature range with power applied, T_A	–65°C to 135°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

	CY54FCT273T			CY74FCT273T			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
I_{OH} High-level output current			–12			–32	mA
I_{OL} Low-level output current			32			64	mA
T_A Operating free-air temperature	–55		125	–40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

CY54FCT273T, CY74FCT273T

8-BIT REGISTERS

SCCS020A – MARCH 1995 – REVISED OCTOBER 2001

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	CY54FCT273T			CY74FCT273T			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_{IN} = -18\text{ mA}$	-0.7	-1.2					V
	$V_{CC} = 4.75\text{ V}$, $I_{IN} = -18\text{ mA}$				-0.7	-1.2		
V_{OH}	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -12\text{ mA}$	2.4	3.3					V
	$V_{CC} = 4.75\text{ V}$				2			
					2.4	3.3		
V_{OL}	$V_{CC} = 4.5\text{ V}$, $I_{OL} = 32\text{ mA}$	0.3	0.55					V
	$V_{CC} = 4.75\text{ V}$, $I_{OL} = 64\text{ mA}$				0.3	0.55		
V_{hys}	All inputs	0.2			0.2			V
I_I	$V_{CC} = 5.5\text{ V}$, $V_{IN} = V_{CC}$			5				μA
	$V_{CC} = 5.25\text{ V}$, $V_{IN} = V_{CC}$						5	
I_{IH}	$V_{CC} = 5.5\text{ V}$, $V_{IN} = 2.7\text{ V}$			± 1				μA
	$V_{CC} = 5.25\text{ V}$, $V_{IN} = 2.7\text{ V}$						± 1	
I_{IL}	$V_{CC} = 5.5\text{ V}$, $V_{IN} = 0.5\text{ V}$			± 1				μA
	$V_{CC} = 5.25\text{ V}$, $V_{IN} = 0.5\text{ V}$						± 1	
I_{off}	$V_{CC} = 0\text{ V}$, $V_{OUT} = 4.5\text{ V}$			± 1			± 1	μA
$I_{OS}^\ddagger$	$V_{CC} = 5.5\text{ V}$, $V_{OUT} = 0\text{ V}$	-60	-120	-225				mA
	$V_{CC} = 5.25\text{ V}$, $V_{OUT} = 0\text{ V}$				-60	-120	-225	
I_{CC}	$V_{CC} = 5.5\text{ V}$, $V_{IN} \leq 0.2\text{ V}$, $V_{IN} \geq V_{CC} - 0.2\text{ V}$	0.1	0.2					mA
	$V_{CC} = 5.25\text{ V}$, $V_{IN} \leq 0.2\text{ V}$, $V_{IN} \geq V_{CC} - 0.2\text{ V}$				0.1	0.2		
ΔI_{CC}	$V_{CC} = 5.5\text{ V}$, $V_{IN} = 3.4\text{ V}^\S$, $f_1 = 0$, Outputs open	0.5	2					mA
	$V_{CC} = 5.25\text{ V}$, $V_{IN} = 3.4\text{ V}^\S$, $f_1 = 0$, Outputs open				0.5	2		

† Typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input ($V_{IN} = 3.4\text{ V}$); all other inputs at V_{CC} or GND

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS			CY54FCT273T			CY74FCT273T			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
I _{CCD} ††	V _{CC} = 5.5 V, Outputs open, One bit switching at 50% duty cycle, $\overline{MR} = V_{CC}$, V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V			0.06	0.12					mA/ MHz
	V _{CC} = 5.25 V, Outputs open, One bit switching at 50% duty cycle, $\overline{MR} = V_{CC}$, V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V						0.06	0.12		
I _C [#]	V _{CC} = 5.5 V, f ₀ = 10 MHz, Outputs open, $\overline{MR} = V_{CC}$	One bit switching at f ₁ = 2.5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V	0.7	1.4					mA
			V _{IN} = 3.4 V or GND	1.2	3.4					
		Eight bits switching at f ₁ = 2.5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V	1.6	3.2					
			V _{IN} = 3.4 V or GND	3.9	12.2					
	V _{CC} = 5.25 V, f ₀ = 10 MHz, Outputs open, $\overline{MR} = V_{CC}$	One bit switching at f ₁ = 5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V				0.7	1.4		
			V _{IN} = 3.4 V or GND				1.2	3.4		
		Eight bits switching at f ₁ = 5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V				1.6	3.2		
			V _{IN} = 3.4 V or GND				3.9	12.2		
C _i				5	10		5	10	pF	
C _O				9	12		9	12	pF	

† Typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

†† This parameter is derived for use in total power-supply calculations.

$I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4$ V)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.

CY54FCT273T, CY74FCT273T 8-BIT REGISTERS

SCCS020A – MARCH 1995 – REVISED OCTOBER 2001

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

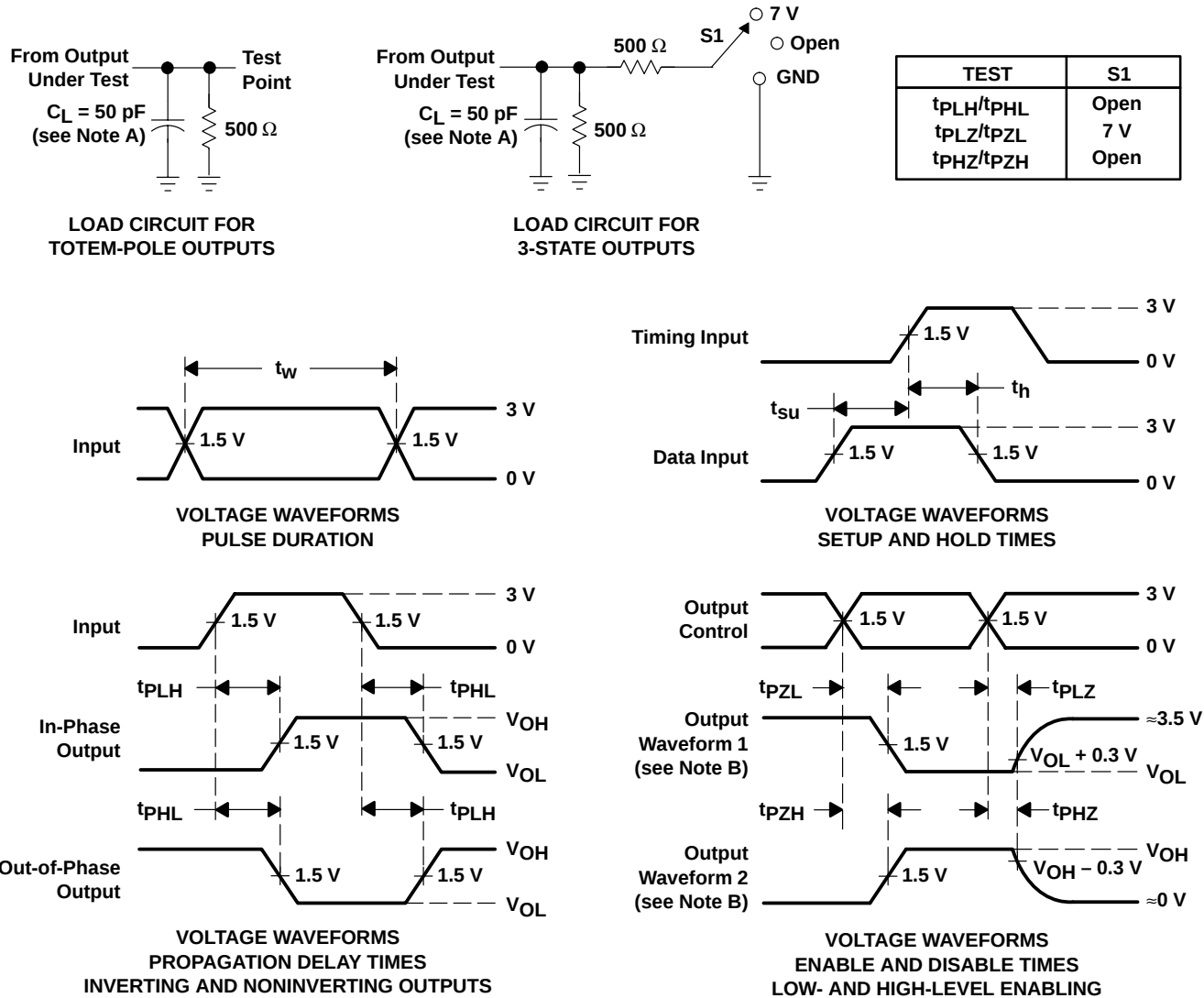
			CY74FCT273T		CY54FCT273AT		CY74FCT273AT		CY74FCT273CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, high or low	CP	6		6		6		6		ns
		$\overline{MR}$	6		6		6		6		
t_{su}	Setup time, high or low	D before CP $\uparrow$	2		2		2		2		ns
t_h	Hold time, high or low	D after CP $\uparrow$	1.5		1.5		1.5		1.5		ns
t_{rec}	Recovery time	$\overline{MR}$ after CP $\uparrow$	2		2.5		2		2		ns

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT273T		CY54FCT273AT		CY74FCT273AT		CY74FCT273CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	CP	Q	2	13	2	8.3	2	7.2	2	5.8	ns
t_{PHL}			2	13	2	8.3	2	7.2	2	5.8	
t_{PLH}	$\overline{MR}$	Q	2	13	2	8.3	2	7.2	2	6.1	ns
t_{PHL}			2	13	2	8.3	2	7.2	2	6.1	



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9221503M2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9221503MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
CY54FCT273ATLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
CY74FCT273ATQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273ATQCTE4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273ATQCTG4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273ATSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273ATSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273ATSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273ATSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273ATSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273ATSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273CTQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273CTQCTE4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273CTQCTG4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273CTSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273CTSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273CTSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CY74FCT273TQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273TQCTE4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273TQCTG4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT273TSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273TSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273TSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273TSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273TSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT273TSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

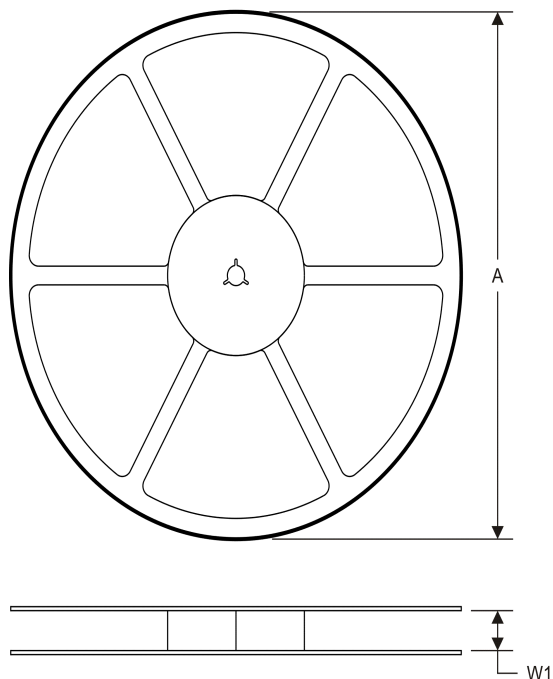
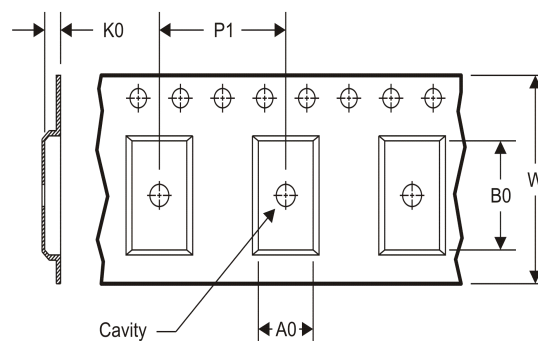
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


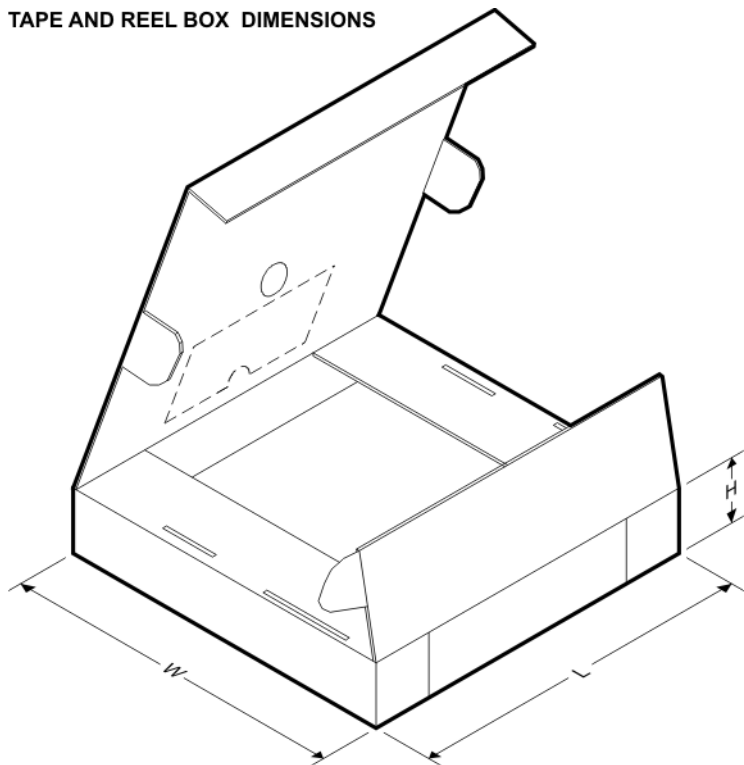
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT273ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT273ATSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CY74FCT273CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT273TQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT273TSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT273ATQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT273ATSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT273CTQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT273TQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT273TSOCT	SOIC	DW	20	2000	367.0	367.0	45.0

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